Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP 10512 Switch Chassis (JC748A)
HP 10512 TAA Switch Chassis (JG823A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE)

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	7
Batteries	All types including standard alkaline and lithium coin or button style batteries	5
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		12
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 2, and then remove the left and right mounting angles 2 from the chassis.
2. Unscrew the screws on front panel 3 and then remove front panel 3 from the chassis.
3. Unscrew the screws on blank panel 4, and then remove blank panel 4 from the chasssis.
4. Unscrew the screws on front panel 5, and then remove front panel 5 from the chassis.
5. Unscrew the screws on power cable channel sets 6, and then remove the power cable channel sets 6 from the chassis.
6. Unscrew the screws on blank power module panel 7, and then remove blank power module panel 7 from the chassis.
7. Unscrew the screws on power module 8, and then remove power module 8 from the chassis.
8. Remove the film 9 from the chassis.
9. Unscrew the screws on dust filter 13,14, and then remove the dust filter 13,14 from the chassis.
10. Unscrew the screws on fan frame 11,12, and then remove fan frame 11,12 from the chassis.
11. Unscrew the screws on net board panel 10, and then remove net board panel 10 from the chassis.
12. Unscrew the screws on panel 15, and then remove panel 15 from the chassis.
13. Unscrew the screws on net blank panel 16, and then remove net blank panel 16 from the chassis.
14. Unscrew the screws on flue panel A 17, and then remove the flue panel A 17 from the chassis.
15. Unscrew the screws on flue panel B 18, and then remove the flue panel B 18 from the chassis.
16. Unscrew the screws on flue panel C 19, and then remove the flue panel C 19 from the chassis.
17. Unscrew the screws on back cover 20, and then remove the back cover 20 from the chassis.
18. Remove shielding finger 21 from the chassis.
19. Unscrew the screws on back up rail 22, and then remove the back up rail 22 from the chassis.
20. Unscrew the screws on back down rail 23, and then remove the back down rail 23 from the chassis.
21. Remove all of the inner cables.
22. Unscrew the screws on PCB 24, and then remove PCB 24.
23. Unscrew the screws on strengthen plate 25, and then remove the strengthen plate 25.
24. Unscrew the screws on PCB 26, and then remove PCB 26.
25. Remove all of the labels and films.
26. Unscrew the screws on wire channel 2-2, and then remove wire channel 2-2 from mounting angle 2-1.
27. Unscrew the screws on pcb 3-2, and then remove pcb 3-3 from front panel 3-1.
28. Remove shielding finger 3-3 from front panel 3-1.
29. Remove film 3-4 from front panel 3-1.
30. Unscrew the screws on part 4-2, and then remove part 4-2 from front blank panel 4-1.
31. Remove shielding finger 4-3 from front blank panel 4-1.
32. Remove film 4-4 from front blank panel 4-1.
33. Unscrew the screws on part 5-2, and then remove part 5-2 from front panel 5-1.
34. Unscrew the screws on pcb 5-3, and then remove pcb 5-3 from front panel 5-1.
35. Remove shielding finger 5-4 from front panel 5-1.
36. Remove film 5-5 from front panel 5-1.
37. Unscrew the screws on power cable channel sets 6, and then remove the blocks 6-2 from wire road board 6-1
38. Unscrew the screws on part 11-1, and then remove the part 11-7 from fan frame 11-1.
39. Unscrew the screws on pcb 11-6, and then remove the pcb 11-6 from the part 11-1.
40. Remove the EMIS 11-5,11-4 from the fan frame 11-1.
41. Unscrew the screws on part 11-1,and then remove the handle 11-3 from the part11-1.
42. Remove the film 11-2 from the part 11-1.
43. Unscrew the screws on part 12-1, and then remove the part 12-7 from fan frame 12-1.
44. Unscrew the screws on pcb 12-6, and then remove the pcb 12-6 from the part 12-1.
45. Remove the EMIS 12-5,12-4 from the fan frame 12-1.
46. Unscrew the screws on part 12-1,and then remove the handle 12-3 from the part12-1.

47. Remove the film 12-2 from the part 12-1.
48. Unscrew the screws on pcb 10-2, and then remove pcb 10-2 from front panel 10-1.
49. Unscrew the screws on part 10-3, and then remove part 10-3 from front panel 10-2.
50. Remove shielding finger 10-4 from front panel 10-1.
51. Remove film 10-5 from front panel 10-1.
52. Unscrew the screws on part 16-2, and then remove part1 16-2 from net blank panel16-1.
53. Remove shielding finger 16-3 from net blank panel 16-1.
54. Remove film 16-4 from net blank panel 16-1.
55. Unscrew the screws on part 17-2, and then remove part 17-2 from flue panel A 17-1.
56. Remove shielding finger 17-3 from flue panel A 17-1.
57. Unscrew the screws on part 18-2, and then remove part 18-2 from flue panel B 18-1.
58. Remove shielding finger 18-3 from flue panel B 18-1.
59. Unscrew the screws on part 18-2, and then remove part 19-2 from flue panel C 19-1.
60. Remove shielding finger 19-3 from flue panel C 19-1.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

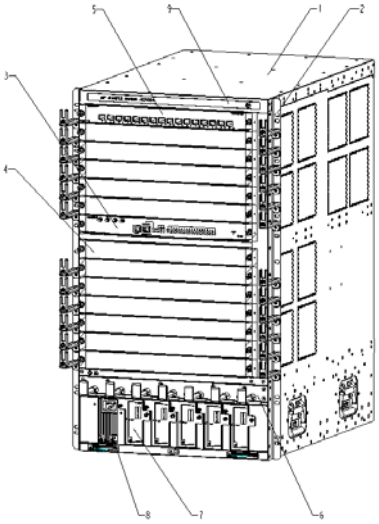


Figure 1 Treatments to the product (front view)

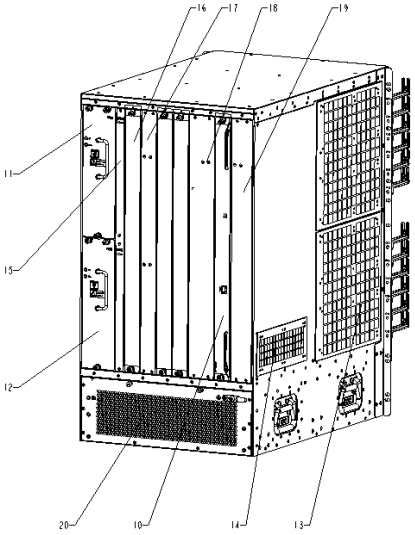
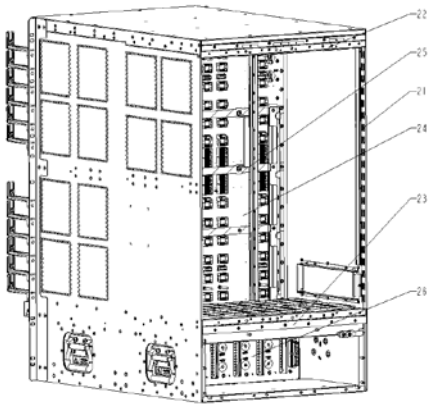


Figure 2 Treatments to the product (rear view)



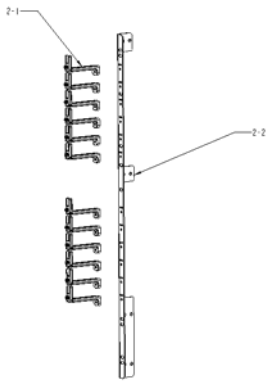


Figure 3 Treatments to the product (rear view)

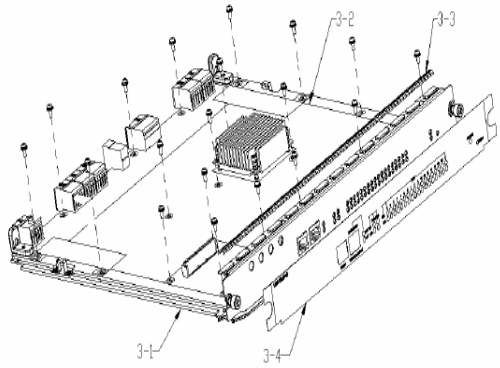


Figure 4 Treatments to mounting angle 2

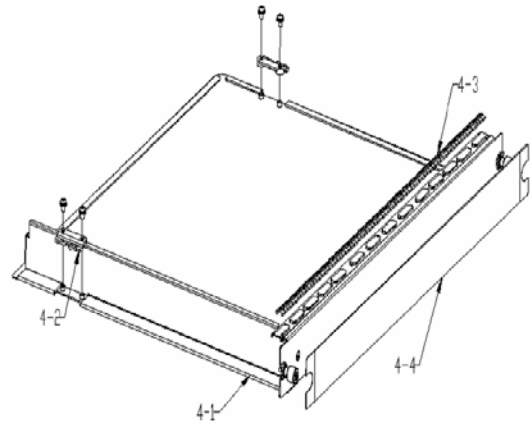
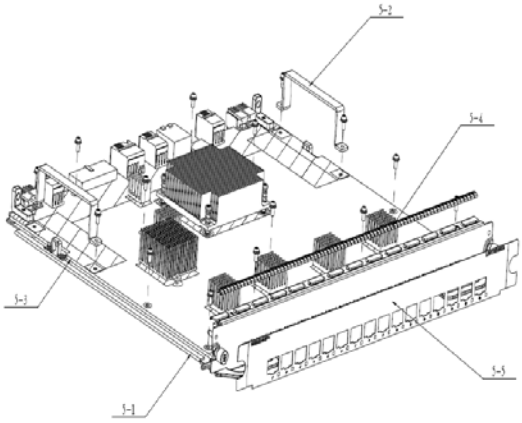


Figure 5 Treatments to front panel 3

Figure 6 Treatments to front blank panel 4



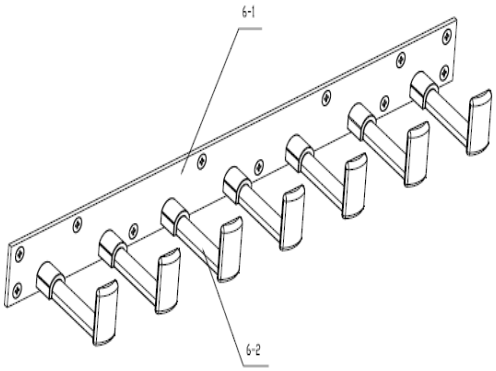
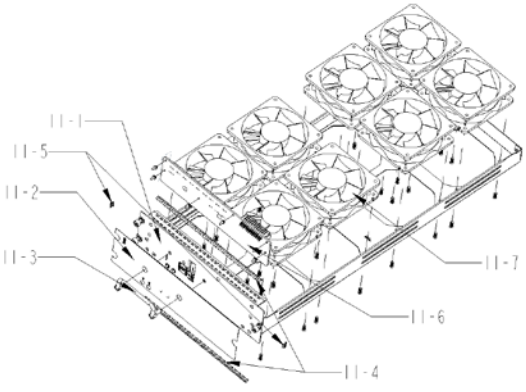


Figure 7 Treatments to front panel 5

Figure 8 Treatments to upper wire channel sets 6



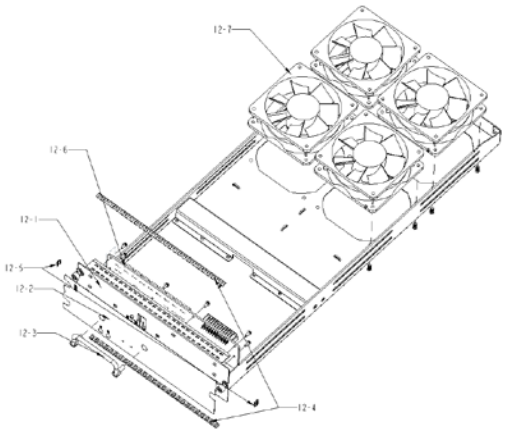


Figure 9 Treatments to up fan frame 11

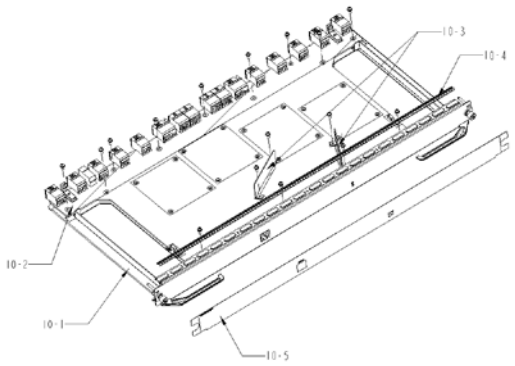


Figure 10 Treatments to down fan frame 12

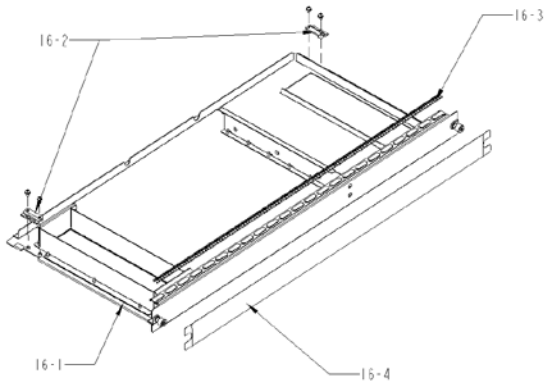
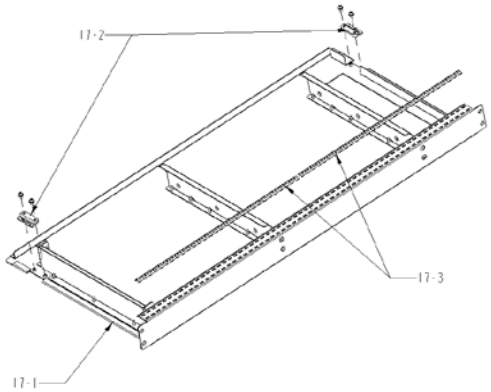


Figure 11 Treatments to net board panel 10

Figure 12 Treatments to net blank panel 16



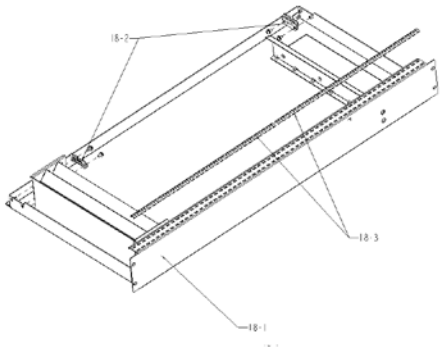


Figure 13 Treatments to flue panel A 17

Figure 14 Treatments to flue panel B 18

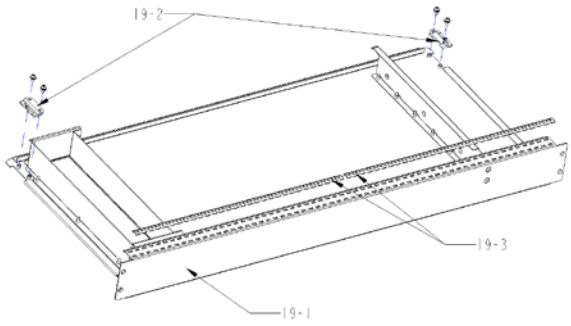


Figure 15 Treatments to flue panel C 19

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
	1	Fe	45609	47.96%		Fe recycling
2						
	2-1	Fe	182	0.19%		Fe recycling
	2-2	Al	30*24	1.63%		Al recycling
3						
	3-1	Fe	1520	1.59%		Fe recycling
	3-2	Complex PWB	1300	1.36%	The surface of PCB is greater than 10 square centimeters;	
	3-2	Be-Cu	4.3	0.00%		Cu recycling
	3-4	PC	2	0.00%	Containing brominated flame retardants	
4						
	4-1	Fe	1550	1.59%		Fe recycling
	4-2	PA	2	0.00%		Pla recycling
	4-3	Be-Cu	4.3	0.00%		Cu recycling
	4-4	PC	2	0.00%	Containing brominated flame retardants	

5						
	5-1	Fe	1520	1.59%		Fe recycling
	5-2	Fe	25*2	0.05%		Fe recycling
	5-3	Complex PWB	1900	1.99%	The surface of PCB is greater than 10 square centimeters;	
	5-4	Be-Cu	4.3	0.00%		Cu recycling
	5-5	PC	2	0.00%	Containing brominated flame retardants	
6						
	6-1	Fe	313.7	0.32%		Fe recycling
	6-2	Al	25.12*7	0.20%		Al recycling
	7	Fe	130	0.13%		Fe recycling
	8		2500	2.62%		
	9	PC	2.24	0.00%	Containing brominated flame retardants	
10						
	10-1	Fe	2200	1.35%		Fe recycling
	10-2	Complex PWB	1500	1.57%	The surface of PCB is greater than 10 square centimeters;	

	10-3	Fe	20	0.02%		Fe recycling
	10-4	Be-Cu	4.3	0.00%		Cu recycling
	10-5	PC	2	0.00%	Containing brominated flame retardants	
11						
	11-1	Fe	2370	2.49%		Fe recycling
	11-2	PC	9.8	0.00%	Containing brominated flame retardants	
	11-3	Al	37	0.03%		Al recycling
	11-4	Be-Cu	4.5	0.00%		Cu recycling
	11-5	Be-Cu	2	0.00%		Cu recycling
	11-6	Complex PWB	120	0.12%	The surface of PCB is greater than 10 square centimeters;	
	11-7		350*8	2.85%		
12						
	12-1	Fe	2560	2.69%		Fe recycling
	12-2	PC	9.9	0.00%	Containing brominated flame retardants	
	12-3	Al	37	0.03%		Al recycling

	12-4	Be-Cu	4.5	0.00%		Cu recycling
	12-5	Be-Cu	2	0.00%		Cu recycling
	12-6	Complex PWB	122	0.12%	The surface of PCB is greater than 10 square centimeters;	
	12-7		350*4	1.40%		
	13	Fe	383	0.41%		Fe recycling
	14	Fe	1010	1.06%		Fe recycling
	15	Fe	3470	3.64%		Fe recycling
16						
	16-1	Fe	2200	2.32%		Fe recycling
	16-2	PA	2	0.00%		Pla recycling
	16-3	Be-Cu	4.5	0.00%		Cu recycling
	16-4	PC	2	0.00%	Containing brominated flame retardants	
17						
	17-1	Fe	2250	2.36%		Fe recycling
	17-2	PA	2	0.00%		Pla recycling

	17-3	Be-Cu	4.5	0.00%		Cu recycling
18						
	18-1	Fe	2610	2.74%		Fe recycling
	18-2	PA	2	0.00%		Pla recycling
	18-3	Be-Cu	4.5	0.00%		Cu recycling
19						
	19-1	Fe	2130	2.24%		Fe recycling
	19-2	PA	2	0.00%		Pla recycling
	19-3	Be-Cu	4.5	0.00%		Cu recycling
	20	Fe	775	0.81%		Fe recycling
	21	PC	0.65	0.00%	Containing brominated flame retardants	
	22	Fe	1970	2.07%		Fe recycling
	23	Fe	2650	2.78%		Fe recycling
	24	Fe	150*2	0.03%		Fe recycling
	25	Complex PWB	4650	4.89%	The surface of PCB is greater than 10 square centimeters;	

	26	Complex PWB	650	0.60%	The surface of PCB is greater than 10 square centimeters;	

4. Revised record

Date	Version	Author	Modify content
2012.04.20	V0	Xiao Dujun	Initial version
2013.10.14	V1	Chen Longjun	Add the module JG823A relation